

12-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER WITH INTERNAL PULLDOWN RESISTORS

SCDS052D – MARCH 1998 – REVISED MAY 2000

- **TTL-Compatible Control Input Levels**
- **Isolation Under Power-Off Conditions**
- **Make-Before-Break Feature**
- **Internal 500- Ω Pulldown Resistors to Ground**
- **A-Port Inputs/Outputs Have Equivalent 25- Ω Series Resistors, So No External Resistors Are Required**
- **Latch-Up Performance Exceeds 250 mA Per JESD 17**
- **Package Options Include Plastic Thin Shrink Small-Outline (DGG), Thin Very Small-Outline (DGV), and Shrink Small-Outline (DL) Packages**

description

The SN74CBT162292 is a 12-bit 1-of-2 high-speed TTL-compatible FET multiplexer/demultiplexer. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

When the select (S) input is low, port A is connected to port B1, and R_{INT} is connected to port B2. When S is high, port A is connected to port B2, and R_{INT} is connected to port B1.

The A-port inputs/outputs include equivalent 25- Ω series resistors to reduce overshoot and undershoot.

The SN74CBT162292 is characterized for operation from -40°C to 85°C .

DGG, DGV, OR DL PACKAGE (TOP VIEW)

S	1	56	NC
1A	2	55	NC
NC	3	54	1B1
2A	4	53	1B2
NC	5	52	2B1
3A	6	51	2B2
NC	7	50	3B1
GND	8	49	GND
4A	9	48	3B2
NC	10	47	4B1
5A	11	46	4B2
NC	12	45	5B1
6A	13	44	5B2
NC	14	43	6B1
7A	15	42	6B2
NC	16	41	7B1
V _{CC}	17	40	7B2
8A	18	39	8B1
GND	19	38	GND
NC	20	37	8B2
9A	21	36	9B1
NC	22	35	9B2
10A	23	34	10B1
NC	24	33	10B2
11A	25	32	11B1
NC	26	31	11B2
12A	27	30	12B1
NC	28	29	12B2

NC – No internal connection

FUNCTION TABLE

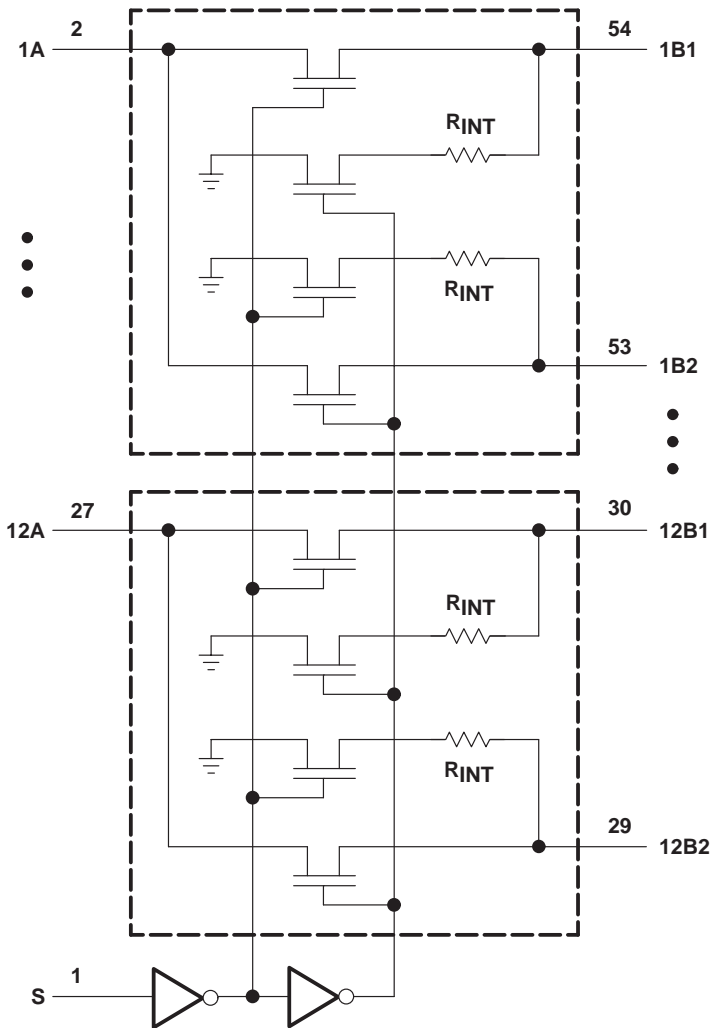
INPUT S	FUNCTION
L	A port = B1 port R_{INT} = B2 port
H	A port = B2 port R_{INT} = B1 port

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

SN74CBT162292
 12-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER
 WITH INTERNAL PULLDOWN RESISTORS

SCDS052D – MARCH 1998 – REVISED MAY 2000

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	−0.5 V to 7 V
Input voltage range, V_I (see Note 1)	−0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_I < 0$)	−50 mA
Package thermal impedance, θ_{JA} (see Note 2):	
DGG package	64°C/W
DGV package	48°C/W
DL package	56°C/W
Storage temperature range, T_{stg}	−65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 2. The package thermal impedance is calculated in accordance with JESD 51.

SN74CBT162292
12-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER
WITH INTERNAL PULLDOWN RESISTORS
SCDS052D – MARCH 1998 – REVISED MAY 2000

recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
V_{CC} Supply voltage	4	5.5	V
V_{IH} High-level control input voltage	2		V
V_{IL} Low-level control input voltage		0.8	V
T_A Operating free-air temperature	-40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP†	MAX	UNIT
V _{IK}		V _{CC} = 4.5 V,	I _I = −18 mA			−1.2	V
I _I		V _{CC} = 5.5 V,	V _I = V _{CC} or GND			±5	μA
I _{off}		V _{CC} = 0,	V _I or V _O = 0 to 7 V			10	μA
I _{CC}		V _{CC} = 5.5 V,	I _O = 0, V _I = V _{CC} or GND			3	μA
ΔI _{CC} ‡	Control input	V _{CC} = 5.5 V,	One input at 3.4 V, Other inputs at V _{CC} or GND			2.5	mA
C _i	Control input	V _I = 3 V or 0				3.5	pF
C _{io}		V _{CC} = 0, V _O = 3 V or 0				8	pF
r _{on} §		V _{CC} = 4 V, TYP at V _{CC} = 4 V	V _I = 2.4 V, I _I = 15 mA			38 55	Ω
		V _{CC} = 4.5 V	V _I = 0	I _I = 45 mA		39 63	
				I _I = 30 mA		37 55	
				V _I = 2.4 V, I _I = 15 mA		37 55	

† All typical values are at $V_{CC} = 5\text{ V}$ (unless otherwise noted), $T_A = 25^\circ\text{C}$.

‡ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

§ Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

switching characteristics over recommended operating free-air temperature range, $C_L = 50\text{ pF}$, (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4\text{ V}$		$V_{CC} = 5\text{ V} \pm 0.5\text{ V}$		UNIT
			MIN	MAX	MIN	MAX	
t_{pd}^\P	A or B	B or A		1.9		1.85	ns
t_{en}	S	A or B	1	10.7	1	9.5	ns
t_{dis}	S	A or B	1	10.9	1	9.7	ns

† The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

switching characteristics over recommended operating free-air temperature range, $C_L = 50\text{ pF}$, (unless otherwise noted) (see Figure 1)

PARAMETER	DESCRIPTION	$V_{CC} = 4\text{ V}$		$V_{CC} = 5\text{ V} \pm 0.5\text{ V}$		UNIT
		MIN	MAX	MIN	MAX	
$t_{mbb}^\#$	Make-before-break time	0	2	0	2	ns

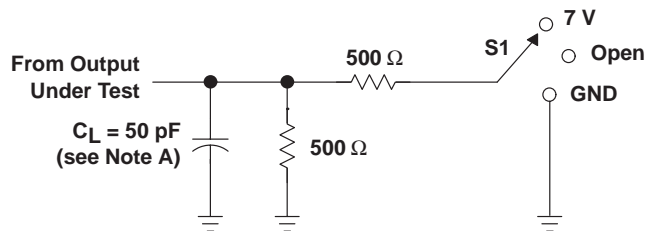
The make-before-break time is the time interval between make and break, during the transition from one selected port to the other.

SN74CBT162292

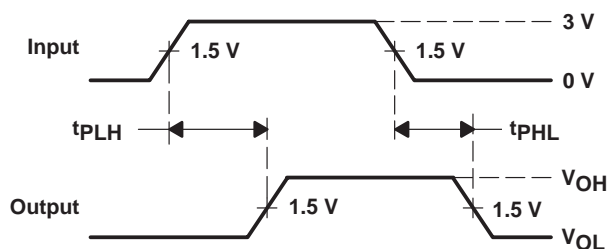
12-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER WITH INTERNAL PULLDOWN RESISTORS

SCDS052D – MARCH 1998 – REVISED MAY 2000

PARAMETER MEASUREMENT INFORMATION

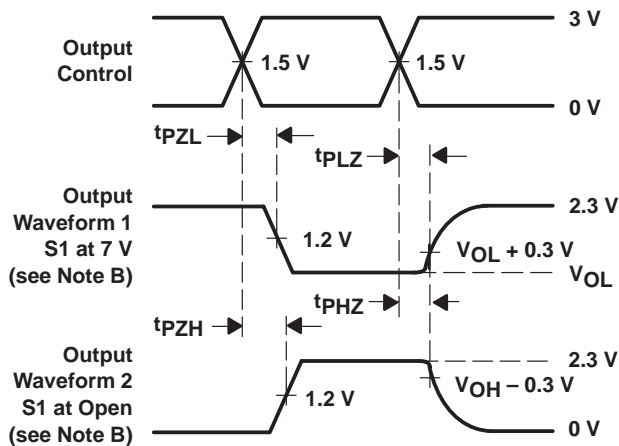


LOAD CIRCUIT



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES

TEST	S1
t_{pd}	Open
t_{PZL}/t_{PLZ}	7 V
t_{PZH}/t_{PHZ}	Open



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low except when connected to the internal 500- Ω pulldown resistor. Waveform 2 is for an output with internal conditions such that the output is high except when connected to the internal 500- Ω pulldown resistor.
 - All pulse inputs and DC inputs are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - The outputs are measured one at a time with one transition per measurement.
 - t_{PLZ} and t_{PHZ} are the same as t_{dis} . $Z = R_{INT} = 500 \Omega$.
 - t_{PZL} and t_{PZH} are the same as t_{en} . $Z = R_{INT} = 500 \Omega$.
 - t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

IMPORTANT NOTICE

Texas Instruments and its subsidiaries (TI) reserve the right to make changes to their products or to discontinue any product or service without notice, and advise customers to obtain the latest version of relevant information to verify, before placing orders, that information being relied on is current and complete. All products are sold subject to the terms and conditions of sale supplied at the time of order acknowledgment, including those pertaining to warranty, patent infringement, and limitation of liability.

TI warrants performance of its semiconductor products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are utilized to the extent TI deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except those mandated by government requirements.

Customers are responsible for their applications using TI components.

In order to minimize risks associated with the customer's applications, adequate design and operating safeguards must be provided by the customer to minimize inherent or procedural hazards.

TI assumes no liability for applications assistance or customer product design. TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right of TI covering or relating to any combination, machine, or process in which such semiconductor products or services might be or are used. TI's publication of information regarding any third party's products or services does not constitute TI's approval, warranty or endorsement thereof.